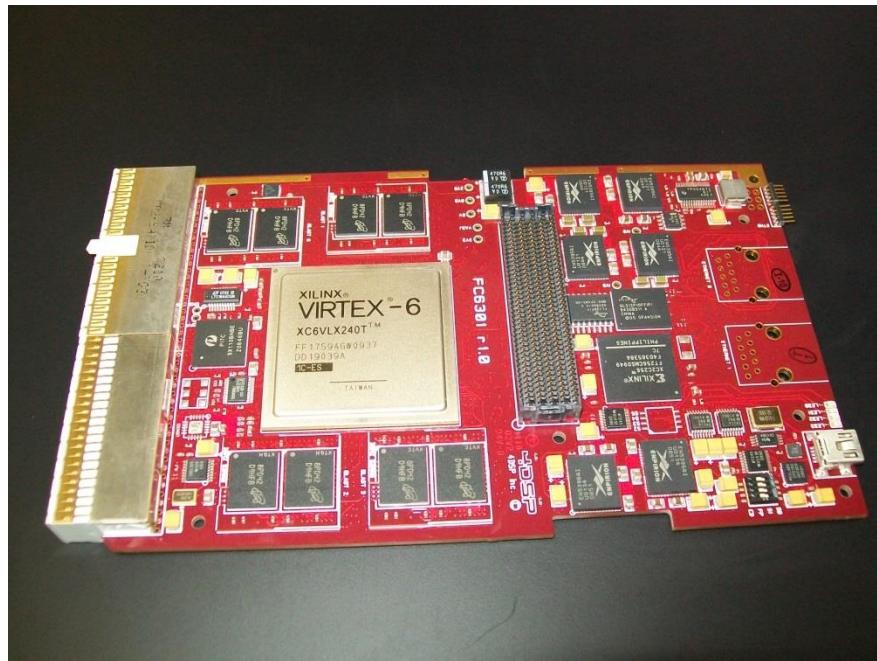


FC6301

User Manual



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Revision History

Date	Revision	Revision
2010-10-05	Draft	0.1
2010-11-21	Release	1.0
2013-04-08	Added the FMC pinout tables	1.1
2013-05-01	Updated Table 5: FMC GTX/GTH connections to use the MGTx_abc notation. Also fixed wrong reference to MGT bank 115 and changed it to MGT bank 113	1.2
2014-04-15	Added “Table 2: P2 connections” and updated section 4.1 with a description of the P2 connector limitation.	1.3

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1 Acronyms and related documents

1.1 Acronyms

A/D	Analog to Digital Converter
BLAST	Board Level Advanced Scalable Technology
CPLD	Complex Programmable Logic Device
D/A	Digital to Analog Converter
DCI	Digitally Controlled Impedance
DDR	Double Data Rate
DSP	Digital Signal Processing
FBGA	Fineline Ball Grid Array
FFT	Fast Fourier Transformation
FMC	FPGA Mezzanine Card
FPDP	Front Panel Data Port
FPGA	Field Programmable Gate Array
GPIO	General Purpose Input/Output
GUI	Graphical User Interface
HPC	High pin count
IP	Intellectual Property
JTAG	Joint Test Action Group
LED	Light Emitting Diode
LSB	Least Significant Bit(s)
LVDS	Low Voltage Differential Signaling
LVTTL	Low Voltage Transistor Logic level
MGT	Multi-Gigabit Transceiver
MSB	Most Significant Bit(s)
PCB	Printed Circuit Board
PCI	Peripheral Component Interconnect
PCIe	PCI Express
PLL	Phase Locked Loop
pps	Pulse Per Second
QDR	Quadruple Data rate
SDRAM	Synchronous Dynamic Random Access memory
sFPDP	Serial FPDP
SPI	Serial Peripheral Interconnect
SRAM	Synchronous Random Access memory
SRIO	Serial Input/Output
SSC	Spread Spectrum Clocking
TTL	Transistor Logic level
UART	Universal Asynchronous Receiver/Transmitter
USB	Universal Serial Bus

Table 1: Glossary

1.2 Related Documents

- 3U CompactPCI specifications (PICMG 2.0 R3.0)
- CompactPCI Hot Swap specifications (PICMG 2.1 R2.0)
- VITA 57.1 FPGA Mezzanine Card Standard
- Xilinx Virtex-6 documentation

2 General description

The FC6301 is a high performance CompactPCI (cPCI) card with advanced digital signal processing capabilities. The design has been targeted for customer programmable implementations of complex FPGA algorithms for Digital Signal Processing (DSP) applications. The FC6301 product is in the 3U cPCI form factor, offering various direct on-board interface options that are closely coupled to large - fast on-board memory resources of the Xilinx Virtex™-6 FPGA. The FC6301 is an excellent choice for high performance applications that require the use of accelerated frequency-domain algorithms such as with FFTs. 4DSP has many off-the-shelf Intellectual Property (IP) cores for applications that require the highest level of performance. CompactPCI (cPCI) is an adaptation of the Peripheral Component Interconnect (PCI) Specification for industrial and military embedded applications requiring a more robust mechanical form factor than a desktop PC.

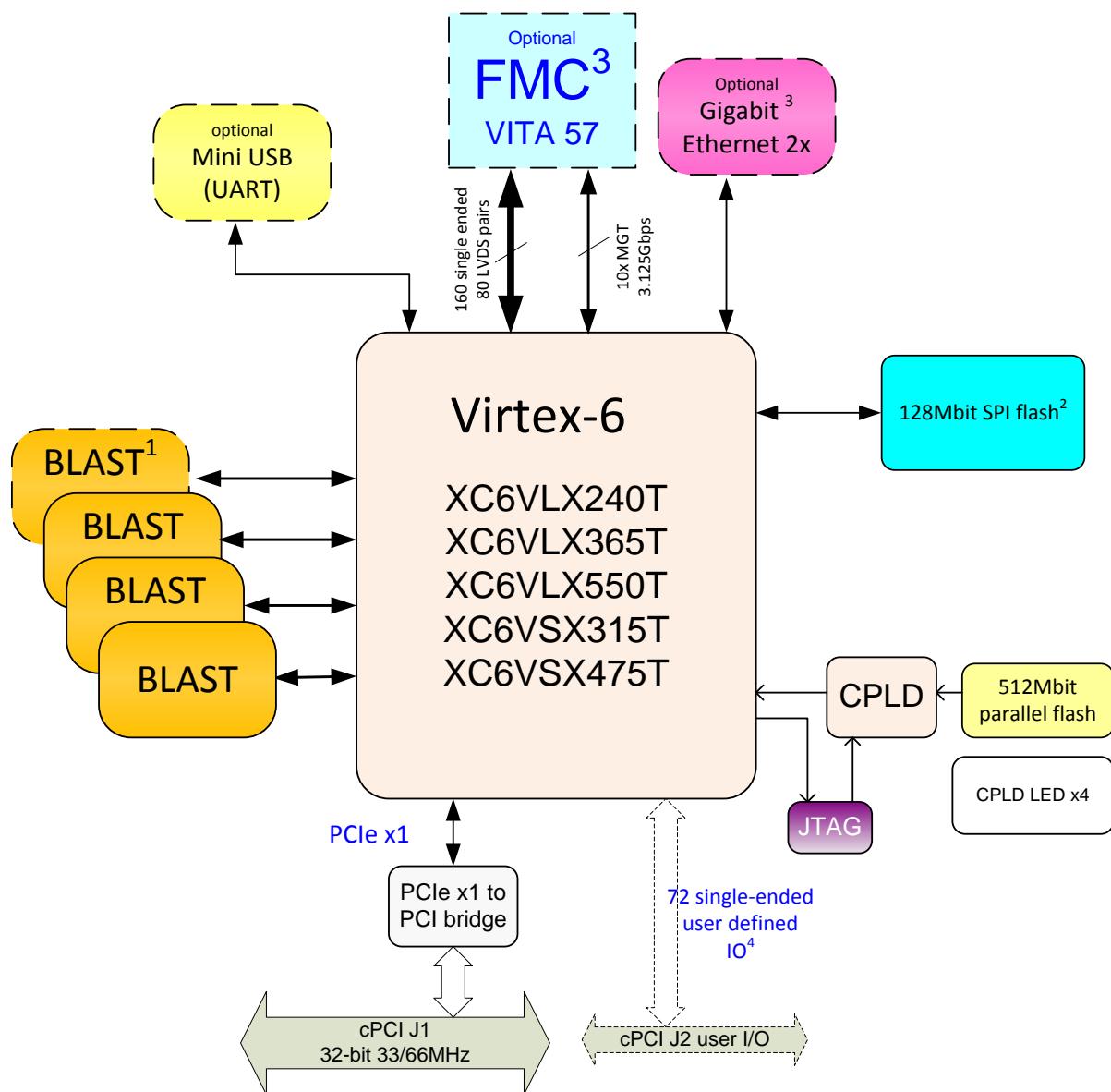


Figure 1: FMC122 block diagram

¹ 4th BLAST site only fully supported on SX475T and LX550T devices, on other devices only the DDR2 BLAST (A) is supported.

² Refer to the Appendix for Errata.

³ FMC and Ethernet are mutually exclusive. Either Ethernet or FMC can be used.

⁴ Default configuration does not mount series zero ohm resistors, contact factory if J2 connections are required.

3 Installation

3.1 Requirements and handling instructions

- The FC6301 daughter card must be installed cPCI backplane compliant to the cPCI standard.
- Do not flex the board and prevent electrostatic discharges by observing ESD precautions when handling the card.

3.2 Firmware and Software

Drivers, API libraries and a program example working in combination with a pre-programmed firmware for the FPGA is provided. The FC6301 is delivered with an interface to the Xilinx PClexpress endpoint in the Virtex-6 device and an example VHDL design so users can start performing data transfers over the PCI bus right out of the box. For more information about software installation and FPGA firmware, please refer the 4FM Get Started Guide.

4 Hardware Specification

4.1 Phycisal specifications

The FC6301 card complies with the compact PCI standard known as PICMG 2.0 R3.0. The card is a 3U (100 mm by 160 mm) module which incorporates a 32 bits PCI bus on the P1 connector. The P2 connector is fully routed to the Virtex6 FPGA through zero ohm resistors. However the LX240T version of the Virtex6 FPGA does not completely support the P2 connector. Table 2 lists the signals the connections of P2 and which signals are not available on the LX240T. Also addition: the zero ohm resistors are not mounted by default, contact factory in case connections on P2 are required.

4.1.1 Front panel layout

There are three front panel options. One front panel is used when an FMC board is mounted. The other front panel is used when the Ethernet IO option is chosen. And the third option has no cutout at all.

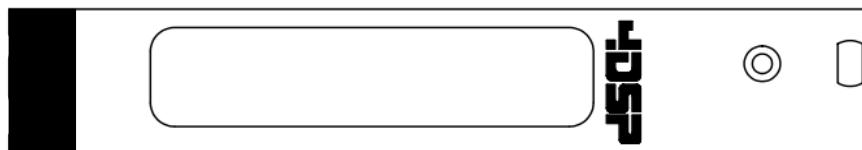


Figure 2: FMC option Bezel drawing

4.1.2 P2 connections

FPGA Pin	P2 pin #	Signal name	Bank Voltage	Notes
AT26	A1	FP_RTM_0	1.8V	Not available on LX240T
AU27	A2	FP_RTM_1	1.8V	Not available on LX240T
AK23	B6	FP_RTM_10	1.8V	Not available on LX240T
BB26	B8	FP_RTM_11	1.8V	Not available on LX240T
BB27	B10	FP_RTM_12	1.8V	Not available on LX240T
AM23	C1	FP_RTM_13	1.8V	Not available on LX240T
AN23	C3	FP_RTM_14	1.8V	Not available on LX240T
AU23	C4	FP_RTM_15	1.8V	Not available on LX240T
AU24	C6	FP_RTM_16	1.8V	Not available on LX240T
AP25	C8	FP_RTM_17	1.8V	Not available on LX240T
AP26	C10	FP_RTM_18	1.8V	Not available on LX240T
AK24	D1	FP_RTM_19	1.8V	Not available on LX240T
AK22	A3	FP_RTM_2	1.8V	Not available on LX240T
AL25	D2	FP_RTM_20	1.8V	Not available on LX240T
AP23	D3	FP_RTM_21	1.8V	Not available on LX240T
AR23	D5	FP_RTM_22	1.8V	Not available on LX240T
AM24	D7	FP_RTM_23	1.8V	Not available on LX240T
AL24	D9	FP_RTM_24	1.8V	Not available on LX240T
BA25	D11	FP_RTM_25	1.8V	Not available on LX240T
AN24	E1	FP_RTM_26	1.8V	Not available on LX240T
AN25	E2	FP_RTM_27	1.8V	Not available on LX240T
AV26	E3	FP_RTM_28	1.8V	Not available on LX240T
AU26	E4	FP_RTM_29	1.8V	Not available on LX240T
AJ22	A7	FP_RTM_3	1.8V	Not available on LX240T
AR24	E5	FP_RTM_30	1.8V	Not available on LX240T
AT24	E6	FP_RTM_31	1.8V	Not available on LX240T
AW25	E7	FP_RTM_32	1.8V	Not available on LX240T
AW26	E8	FP_RTM_33	1.8V	Not available on LX240T
AT25	E9	FP_RTM_34	1.8V	Not available on LX240T
AR25	E10	FP_RTM_35	1.8V	Not available on LX240T
H24	A12	FP_RTM_36	1.8V	Not available on LX240T
G24	A13	FP_RTM_37	1.8V	Not available on LX240T
E27	A14	FP_RTM_38	1.8V	Not available on LX240T
D27	A15	FP_RTM_39	1.8V	Not available on LX240T
AY27	A8	FP_RTM_4	1.8V	Not available on LX240T
F25	A16	FP_RTM_40	1.8V	Not available on LX240T
F24	A17	FP_RTM_41	1.8V	Not available on LX240T
C28	A18	FP_RTM_42	1.8V	Not available on LX240T
B28	A19	FP_RTM_43	1.8V	Not available on LX240T

H26	A20	FP_RTM_44	1.8V	Not available on LX240T
G26	A21	FP_RTM_45	1.8V	Not available on LX240T
F26	B12	FP_RTM_46	1.8V	Not available on LX240T
K25	B14	FP_RTM_47	1.8V	Not available on LX240T
J25	B16	FP_RTM_48	1.8V	Not available on LX240T
B27	B18	FP_RTM_49	1.8V	Not available on LX240T
AW27	A9	FP_RTM_5	1.8V	Not available on LX240T
A27	B19	FP_RTM_50	1.8V	Not available on LX240T
J23	B20	FP_RTM_51	1.8V	Not available on LX240T
K23	C12	FP_RTM_52	1.8V	Not available on LX240T
M19	C14	FP_RTM_53	1.8V	Not available on LX240T
N19	C15	FP_RTM_54	1.8V	Not available on LX240T
N21	C16	FP_RTM_55	1.8V	Not available on LX240T
M21	C17	FP_RTM_56	1.8V	Not available on LX240T
A26	C18	FP_RTM_57	1.8V	Not available on LX240T
A25	C19	FP_RTM_58	1.8V	Not available on LX240T
C26	C20	FP_RTM_59	1.8V	Not available on LX240T
AM22	A10	FP_RTM_6	1.8V	Not available on LX240T
D26	C21	FP_RTM_60	1.8V	Not available on LX240T
M22	D13	FP_RTM_61	1.8V	Not available on LX240T
B26	D15	FP_RTM_62	1.8V	Not available on LX240T
C25	D17	FP_RTM_63	1.8V	Not available on LX240T
N23	D19	FP_RTM_64	1.8V	Not available on LX240T
M24	D21	FP_RTM_65	1.8V	Not available on LX240T
D25	E11	FP_RTM_66	1.8V	Not available on LX240T
E25	E12	FP_RTM_67	1.8V	Not available on LX240T
P21	E13	FP_RTM_68	1.8V	Not available on LX240T
P22	E14	FP_RTM_69	1.8V	Not available on LX240T
AL22	A11	FP_RTM_7	1.8V	Not available on LX240T
P20	E15	FP_RTM_70	1.8V	Not available on LX240T
N20	B21	FP_RTM_71	1.8V	Not available on LX240T
BA26	B2	FP_RTM_8	1.8V	Not available on LX240T
AJ23	B4	FP_RTM_9	1.8V	Not available on LX240T
K42	A6	FP_RTM_CLKinn	2.5V	
J42	A5	FP_RTM_CLKinp	2.5V	
P31	E21	FP_RTM_CLKoutn	2.5V	
P30	E20	FP_RTM_CLKoutp	2.5V	

Table 2: P2 connections

4.2 cPCI P0 connector

A one lane PCI express is connected to a bridge device (PI7C9X110) thus making the Virtex-6 FPGA available for access on the parallel PCI bus. The following performances have been recorded on the bus.

- **PCI 33 MHz: Host to FC6301 60 Mbytes/s sustained**
- **PCI 33 MHz: FC6301 to Host 110 Mbytes/s sustained**
- **PCI 66 MHz: Host to FC6301 120 Mbytes/s sustained**
- **PCI 66 MHz: FC6301 to Host 140 Mbytes/s sustained**

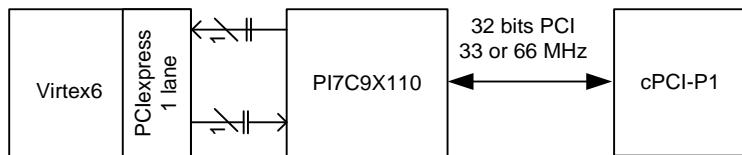


Figure 3 : PCI interface diagram

4.3 Front panel IO

The FC6301 offers different front panel IO options. Not all can be used simultaneously. In case an FMC is used no Ethernet connection is possible.

4.3.1 Gigabit Ethernet

Two Ethernet ports (RJ45 connectors) are available on the FC6301 in the front panel I/O area. The FPGA is connected to a 2-port Ethernet PHY (88E1121) that connects to two RJ45 connectors.

The Gigabit Ethernet ports are capable to adapt to lower Ethernet speeds (10/100) if required. This is a specific option which is not available in combination with an FMC daughter card.

4.3.2 UART

One UART connection will be available on the fontanel via a mini USB connection. The serial interface is made using a USB to UART Bridge (CP2102). The UART will connect directly to the Virtex 6 FPGA via a level translator.

4.3.3 LED

Four LEDs are connected to the CPLD and are available in the front panel I/O area

4.4 FPGA Mezzanine Card (FMC)

The Virtex-6 FPGA interfaces to an FPGA Mezzanine Card (FMC) via a high pin count (HPC) VITA 57.1 site. All the differential and control signals are connected to the Virtex-6 FPGA. The FC6301 also connects all ten high speed differential signals (DP_M2C[9..0] and DP_C2M[9..0]).

The FMC site provides flexibility for adding analog and/or digital IO via customer developed, third party or 4DSP FMC boards. 4DSP offers a wide variety of FMC cards that can be used on the FC6301: <http://www.4dsp.com/fmc.php>

4.4.1 Bank A (LA, HA) connections

Differential routing is applied with matched delay within pairs on bank A (LA, HA).

FPGA Pin	Net Name	FMC HPC	
		Pin Number	Pin Name
AF30	LA_N00_CC	G7	LA00_N_CC
AE30	LA_P00_CC	G6	LA00_P_CC
AK37	LA_N01_CC	D9	LA01_N_CC
AJ37	LA_P01_CC	D8	LA01_P_CC
AK30	LA_N02	H8	LA02_N
AJ31	LA_P02	H7	LA02_P
AJ32	LA_N03	G10	LA03_N
AK33	LA_P03	G9	LA03_P
AG29	LA_N04	H11	LA04_N
AH29	LA_P04	H10	LA04_P
AG39	LA_N05	D12	LA05_N
AF39	LA_P05	D11	LA05_P
AG37	LA_N06	C11	LA06_N
AF37	LA_P06	C10	LA06_P
AG33	LA_N07	H14	LA07_N
AF32	LA_P07	H13	LA07_P
AF41	LA_N08	G13	LA08_N
AF42	LA_P08	G12	LA08_P
AE42	LA_N09	D15	LA09_N
AD42	LA_P09	D14	LA09_P
AD38	LA_N10	C15	LA10_N
AE38	LA_P10	C14	LA10_P
AD30	LA_N11	H17	LA11_N
AD31	LA_P11	H16	LA11_P
Y39	LA_N12	G16	LA12_N
Y40	LA_P12	G15	LA12_P
AA39	LA_N13	D18	LA13_N
Y38	LA_P13	D17	LA13_P

Y37	LA_N14	C19	LA14_N
W37	LA_P14	C18	LA14_P
Y35	LA_N15	H20	LA15_N
AA35	LA_P15	H19	LA15_P
AA30	LA_N16	G19	LA16_N
Y30	LA_P16	G18	LA16_P
AB31	LA_N17_CC	D21	LA17_N_CC
AA31	LA_P17_CC	D20	LA17_P_CC
V30	LA_N18_CC	C23	LA18_N_CC
W30	LA_P18_CC	C22	LA18_P_CC
Y33	LA_N19	H23	LA19_N
W32	LA_P19	H22	LA19_P
Y42	LA_N20	G22	LA20_N
W42	LA_P20	G21	LA20_P
W31	LA_N21	H26	LA21_N
V31	LA_P21	H25	LA21_P
W33	LA_N22	G25	LA22_N
V33	LA_P22	G24	LA22_P
W41	LA_N23	D24	LA23_N
V41	LA_P23	D23	LA23_P
W40	LA_N24	H29	LA24_N
V40	LA_P24	H28	LA24_P
W38	LA_N25	G28	LA25_N
V38	LA_P25	G27	LA25_P
V36	LA_N26	D27	LA26_N
W36	LA_P26	D26	LA26_P
V35	LA_N27	C27	LA27_N
W35	LA_P27	C26	LA27_P
U41	LA_N28	H32	LA28_N
U42	LA_P28	H31	LA28_P
V39	LA_N29	G31	LA29_N
U39	LA_P29	G30	LA29_P
U38	LA_N30	H35	LA30_N
U37	LA_P30	H34	LA30_P
U34	LA_N31	G34	LA31_N
V34	LA_P31	G33	LA31_P
U33	LA_N32	H38	LA32_N
U32	LA_P32	H37	LA32_P
T32	LA_N33	G37	LA33_N
R32	LA_P33	G36	LA33_P

Table 3: FMC LA connections

FPGA Pin	Net Name	FMC HPC	
		Pin Number	Pin Name
AE32	HA_N00_CC	F5	HA00_N_CC
AD32	HA_P00_CC	F4	HA00_P_CC
AJ35	HA_N01_CC	E3	HA01_N_CC
AH34	HA_P01_CC	E2	HA01_P_CC
AM42	HA_N02	K8	HA02_N
AL42	HA_P02	K7	HA02_P
AM41	HA_N03	J7	HA03_N
AL41	HA_P03	J6	HA03_P
AL40	HA_N04	F8	HA04_N
AK40	HA_P04	F7	HA04_P
AL39	HA_N05	E7	HA05_N
AK39	HA_P05	E6	HA05_P
AJ40	HA_N06	K11	HA06_N
AH39	HA_P06	K10	HA06_P
AH41	HA_N07	J10	HA07_N
AG42	HA_P07	J9	HA07_P
AG41	HA_N08	F11	HA08_N
AF40	HA_P08	F10	HA08_P
AF36	HA_N09	E10	HA09_N
AF35	HA_P09	E9	HA09_P
AF34	HA_N10	K14	HA10_N
AG34	HA_P10	K13	HA10_P
AD41	HA_N11	J13	HA11_N
AC41	HA_P11	J12	HA11_P
AE39	HA_N12	F14	HA12_N
AE40	HA_P12	F13	HA12_P
AE35	HA_N13	E13	HA13_N
AE34	HA_P13	E12	HA13_P
AD33	HA_N14	J16	HA14_N
AE33	HA_P14	J15	HA14_P
AC33	HA_N15	F17	HA15_N
AC34	HA_P15	F16	HA15_P
AD40	HA_N16	E16	HA16_N
AC40	HA_P16	E15	HA16_P
AD37	HA_N17_CC	K17	HA17_N_CC
AE37	HA_P17_CC	K16	HA17_P_CC
AB38	HA_N18_CC	J19	HA18_N
AB37	HA_P18_CC	J18	HA18_P

AB36	HA_N19	F20	HA19_N
AC36	HA_P19	F19	HA19_P
AB33	HA_N20	E19	HA20_N
AB32	HA_P20	E18	HA20_P
AB42	HA_N21	K20	HA21_N
AA42	HA_P21	K19	HA21_P
AB41	HA_N22	J22	HA22_N
AA41	HA_P22	J21	HA22_P
AA40	HA_N23	K23	HA23_N
AB39	HA_P23	K22	HA23_P

Table 4: FMC HA connections

4.4.2 Bank B (HB) connections

Differential routing is applied with matched delay within all pairs on bank B (HB).

FPGA Pin	Net Name	FMC HPC	
		Pin Number	Pin Name
P38	HB_N00_CC	K26	HB00_N_CC
R39	HB_P00_CC	K25	HB00_P_CC
M37	HB_N01	J25	HB01_N
M36	HB_P01	J24	HB01_P
L40	HB_N02	F23	HB02_N
L39	HB_P02	F22	HB02_P
M39	HB_N03	E22	HB03_N
M38	HB_P03	E21	HB03_P
L42	HB_N04	F26	HB04_N
L41	HB_P04	F25	HB04_P
N39	HB_N05	E25	HB05_N
N38	HB_P05	E24	HB05_P
P35	HB_N06_CC	K29	HB06_N_CC
P36	HB_P06_CC	K28	HB06_P_CC
P37	HB_N07	J28	HB07_N
N36	HB_P07	J27	HB07_P
M42	HB_N08	F29	HB08_N
M41	HB_P08	F28	HB08_P
R38	HB_N09	E28	HB09_N
T39	HB_P09	E27	HB09_P
N41	HB_N10	K32	HB10_N
N40	HB_P10	K31	HB10_P
P41	HB_N11	J31	HB11_N
P40	HB_P11	J30	HB11_P

R42	HB_N12	F32	HB12_N
P42	HB_P12	F31	HB12_P
T36	HB_N13	E31	HB13_N
U36	HB_P13	E30	HB13_P
T40	HB_N14	K35	HB14_N
R40	HB_P14	K34	HB14_P
T35	HB_N15	J34	HB15_N
T34	HB_P15	J33	HB15_P
T42	HB_N16	F35	HB16_N
T41	HB_P16	F34	HB16_P
J38	HB_N17_CC	K38	HB17_N_CC
K38	HB_P17_CC	K37	HB17_P_CC
K32	HB_N18	J37	HB18_N
K33	HB_P18	J36	HB18_P
P28	HB_N19	E34	HB19_N
N28	HB_P19	E33	HB19_P
K34	HB_N20	F38	HB20_N
K35	HB_P20	F37	HB20_P
L32	HB_N21	E37	HB21_N
L31	HB_P21	E36	HB21_P

Table 5: FMC HB connections

4.4.3 Gigabit transceiver connections

The FC6301 connects the ten DP signals on the FMC connector to gigabit transceivers (GTX blocks) on the FPGA. The reference clock connections are described in section 4.8.1.

FPGA Pin	Net Name	GTX Block	FMC HPC	
			Pin Number	Pin Name
AP4	DP_C2M_N0	MGT0_112	C3	DP0_C2M_N
AP3	DP_C2M_P0		C2	DP0_C2M_P
AN6	DP_M2C_N0		C7	DP0_M2C_N
AN5	DP_M2C_P0		C6	DP0_M2C_P
AN2	DP_C2M_N1	MGT1_112	A23	DP1_C2M_N
AN1	DP_C2M_P1		A22	DP1_C2M_P
AM8	DP_M2C_N1		A3	DP1_M2C_N
AM7	DP_M2C_P1		A2	DP1_M2C_P
AL2	DP_C2M_N2	MGT3_112	A27	DP2_C2M_N
AL1	DP_C2M_P2		A26	DP2_C2M_P
AJ6	DP_M2C_N2		A7	DP2_M2C_N
AJ5	DP_M2C_P2		A6	DP2_M2C_P
AJ2	DP_C2M_N3	MGT1_113	A31	DP3_C2M_N

AJ1	DP_C2M_P3		A30	DP3_C2M_P
AF4	DP_M2C_N3		A11	DP3_M2C_N
AF3	DP_M2C_P3		A10	DP3_M2C_P
AG2	DP_C2M_N4	MGT3_113	A35	DP4_C2M_N
AG1	DP_C2M_P4		A34	DP4_C2M_P
AD4	DP_M2C_N4		A15	DP4_M2C_N
AD3	DP_M2C_P4		A14	DP4_M2C_P
AC2	DP_C2M_N5	MGT1_114	A39	DP5_C2M_N
AC1	DP_C2M_P5		A38	DP5_C2M_P
AB4	DP_M2C_N5		A19	DP5_M2C_N
AB3	DP_M2C_P5		A18	DP5_M2C_P
AE2	DP_C2M_N6	MGT0_114	B37	DP6_C2M_N
AE1	DP_C2M_P6		B36	DP6_C2M_P
AC6	DP_M2C_N6		B17	DP6_M2C_N
AC5	DP_M2C_P6		B18	DP6_M2C_P
AH4	DP_C2M_N7	MGT2_113	B33	DP7_C2M_N
AH3	DP_C2M_P7		B32	DP7_C2M_P
AE6	DP_M2C_N7		B13	DP7_M2C_N
AE5	DP_M2C_P7		B12	DP7_M2C_P
AK4	DP_C2M_N8	MGT0_113	B37	DP8_C2M_N
AK3	DP_C2M_P8		B36	DP8_C2M_P
AG6	DP_M2C_N8		B17	DP8_M2C_N
AG5	DP_M2C_P8		B18	DP8_M2C_P
AM4	DP_C2M_N9	MGT2_112	B37	DP9_C2M_N
AM3	DP_C2M_P9		B36	DP9_C2M_P
AL6	DP_M2C_N9		B17	DP9_M2C_N
AL5	DP_M2C_P9		B18	DP9_M2C_P

Table 6: FMC GTX/GTH connections

4.4.4 Miscellaneous FMC connections

The differential clock connections are described in section 4.8.2. The global address pins (GA0 and GA1) on the FMC site are tied to ground.

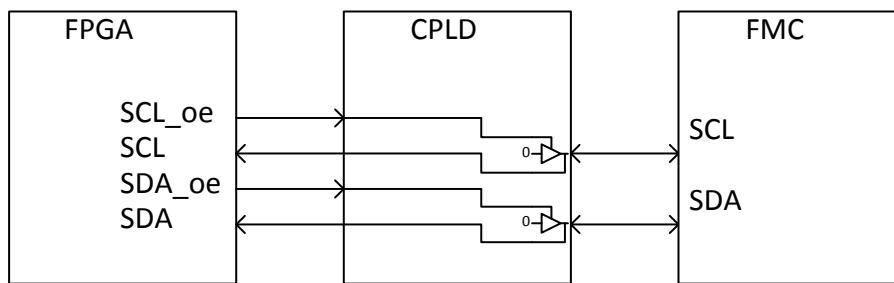
FPGA Pin	Net Name	DIR	FMC HPC	
			Pin Number	Pin Name
Through CPLD	I2C_SCL_FMC	IO	C30	SCL
Through CPLD	I2C_SDA_FMC	IO	C31	SDA
AJ41	PG_M2C	I	F1	PG_M2C

AH40	PRSNT_M2C_L	I	H2	PRSNT_M2C_L
AJ42	PG_C2M	O	D1	PG_C2M

Table 7: Miscellaneous FMC connections

The I/O standard to be assigned depends on VADJ configuration, by default this is 2V5. Contact factory for other VADJ voltages.

The FMC I2C bus signals connect to the CPLD and can be controlled from the FPGA using two signals per I2C line. The connections and CPLD logic are depicted in the following image.

**Figure 4: FMC I2C connections**

FPGA Pin	Net Name	DIR
AT12	SCL_oe	O
BA15	SCL	I
BA14	SDA_oe	O
AR12	SDA	I

Table 8: FMC I2Cconnections

4.5 SPI flash

A 128 Mbits serial flash device (S25FL128P) will be available to the Virtex-6 device. This flash allows the storage of vital data like processor boot code and settings into a non volatile memory.

The flash is operated using a standard SPI interface that can run up to 104 MHz, allowing for a page programming speed up to 208 KB/s. Reading data from the flash can be done at speeds up to 13 MB/s.

The SPI programming pins will be connected to a bank that supports 1V8, whereas the serial flash will be operating at 3V3. This will not cause problems for the signals from the Virtex-6 to the flash device but the signal from the flash device to the Virtex-6 will pass through a level translator (SN74AVC4T245).

4.6 Virtex-6 FPGA device

The Virtex-6 FPGA device is the DSP processing node of the FC6301. The Virtex-6 FPGA device is from the Virtex-6 SXT and LXT family in a 1759 balls fine line ball grid array package. It can be an XC5VLX240T, XC5VLX365T, XC5VLX550T, XC5VSX315T or XC5VSX475T.

4.7 BLAST sites

Thanks to the availability of 3 BLAST sites a wide variety of memory and processing modules can be connected to the Virtex-6 device. For each BLAST site it is possible to choose from the list of available BLAST modules.

For more information about the available BLASTs on the FC6301 please consult the following page: BLAST modules <http://www.4dsp.com/BLAST.htm>

Due to its small form factor and ease of design, the BLAST modules enable a rapid solution for custom memory or processing requirements.

BLAST SITE	1	2	3	4
Single BLAST	YES	YES	YES	YES
Single Extended BLAST	YES	YES	YES	YES
Double BLAST	NO	NO	NO	NO
Double Extended BLAST	NO	NO	NO	NO

Table 9: BLAST Configuration Options

BLAST SITE	1	2	3	4
DDR3	YES	YES	YES	YES
DDR2	YES	YES	YES	YES
QDR	YES	YES	YES	YES
ADV212 JPEG2000	YES	YES	YES	YES
32GB NAND FLASH	YES	YES	YES	YES

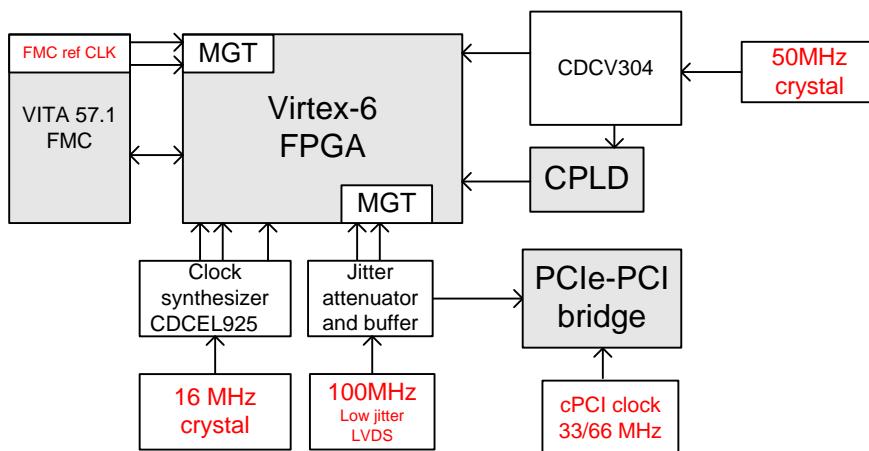
Table 10: BLAST Memory/Processing Options

4.8 Clock tree

The FC6301 clock architecture offers an efficient distribution of low jitter clocks. A 100 MHz clock from a low jitter oscillator is distributed to the FPGA and the PCIexpress to PCI bridge using a PCI express jitter attenuator (ICS847003). This clock is used as the PCIexpress reference clock.

A low jitter programmable clock device (CDCE925) able to generate frequencies from 62.5MHz to 255.5MHz in steps of 0.5MHz is also available. This clock management approach ensures maximum flexibility to efficiently implement multi-clock domains algorithms and use the memory devices at different frequencies.

Further there is also a fixed 50 MHz clock is distributed to the FPGA and the CPLD.

**Figure 5 : Clock tree**

4.8.1 FMC GTX Reference Clock

The FMC standard defines two high precision reference clocks that are driven from the FMC to the carrier. The FC6301 connects these clocks directly to GTX reference clock inputs. The following table shows which GTX/GTHs can use these reference clocks.

FPGA Pin	Net name	GTX REFCLK	GTX/GTHs reached
AK7	GBTCLK0_M2C_n	GTXREFCLK0_112	112, 113
AK8	GBTCLK0_M2C_p		
AD7	GBTCLK1_M2C_n	GTXREFCLK1_113	112, 113, 114
AD8	GBTCLK1_M2C_p		

Table 11: FMC GTX reference clock connections

4.8.2 FMC Clock connections

The FMC clocks are connected to LVDS capable I/O on the FPGA. CLK0 and CLK1 are connected to global clock inputs. CLK2 and CLK3 are connected to regular I/O.

FPGA Pin	Net Name	FMC HPC	
		Pin Number	Pin Name
AN13	CLK0_M2C_n	H5	CLK0_M2C_N
AN14	CLK0_M2C_p	H4	CLK0_M2C_P
AY13	CLK1_M2C_n	G3	CLK1_M2C_N
AY14	CLK1_M2C_p	G2	CLK1_M2C_P
AM12	CLK2_BIDIR_n	K5	CLK2_BIDIR_N
AM13	CLK2_BIDIR_p	K4	CLK2_BIDIR_P
AW16	CLK3_BIDIR_n	J3	CLK3_BIDIR_N
AV16	CLK3_BIDIR_p	J2	CLK3_BIDIR_P

Table 12: FMC clock connections

4.9 FPGA device configuration

4.9.1 Flash storage

The FPGA firmware is stored on board in a flash device. The 512Mbit device is partly used to store the configuration for both FPGAs. In the default CPLD firmware configuration, the Virtex-6 device is directly configured from flash if a valid bitstream is stored in the flash. The flash is pre-programmed in factory with the default firmware example.

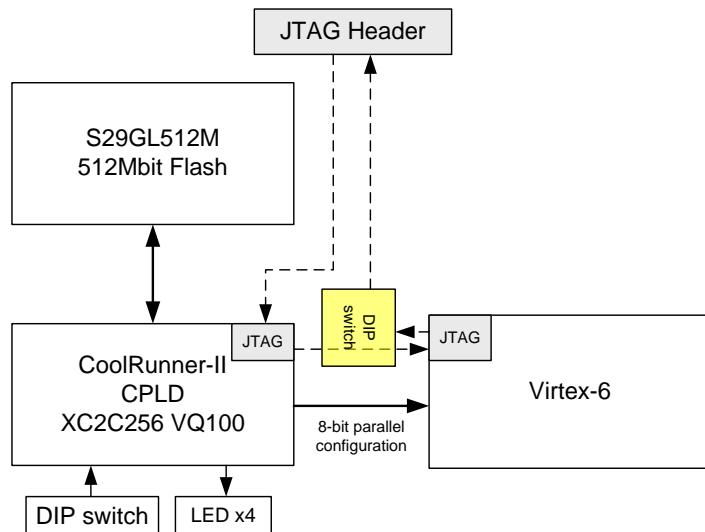


Figure 6 : Configuration circuit

4.9.2 CPLD device

As shown on Figure 4, a CPLD is present on board to interface between the flash device and the FPGA device. It is of type CoolRunner-II. The CPLD is used to program and read the flash. The data stored in the flash is transferred from the host motherboard via the PCI bus to the Virtex-6 device and then to the CPLD that writes the required bit stream to the storage device. A 50MHz clock connects to the CPLD and is used to generate the configuration clock sent to the FPGA device. At power up, if the CPLD detects that an FPGA configuration bitstream is stored in the flash, it will start programming the FPGA device in SelectMap mode.

The CPLD configuration is achieved by loading with a Xilinx download cable a bitstream from a host computer via the JTAG connector. The FPGA device configuration can also be performed using the JTAG chain.

4.9.3 DIP Switch

A switch is located next to the JTAG programming connector. The switch positions are defined as follows:

Sw1	OFF	Default setting. The Virtex-6 configuration is loaded from the flash at power up.
	ON	The Virtex-6 safety configuration is loaded from flash at power up. To be used only if the Virtex-6 cannot be configured from flash or does not perform properly with the switch in the OFF position.
Sw2		Reserved
Sw3		Reserved
Sw4		Reserved

Table 13: Switch description

4.9.4 CPLD LEDs and board status

Four LEDs connect to the CPLD and give information about the board status.

LED 0	Flashing	Virtex-6 FPGA bitstream or user_ROM_register is currently being written to the flash
	ON	Virtex-6 FPGA device not configured
	OFF	Virtex-6 FPGA device
LED 1	ON	Switch 1 is on position ON. The CPLD has been forced to configure the FPGA with the safety configuration
	OFF	Switch 1 is on position OFF.
LED 2	Flashing	The Virtex-6 has been configured with the safety configuration bitstream programmed in the flash at factory because an invalid bitstream was detected in the user configuration space. Please write a valid Virtex-6 device A bitstream to the flash.
	ON	Flash is busy writing or erasing
	OFF	Flash device is not busy
LED 3	ON	CRC error. Presumably a wrong or corrupted FPGA bitstream has been written to the flash. Once on this LED remains on
	OFF	No CRC error detected

Table 14: LED board status

4.9.5 JTAG

A JTAG connector footprint is available on the FC6301 for configuration purposes and the JTAG chain can be accessed using a press-fit JTAG connector. The JTAG chain is connected via a DIP switch that enables the following configurations:

- CPLD -> FPGA
- CPLD only

The JTAG connector can be placed on both sides of the PCB. The connector location seen from the top of the PCB is shown in Figure 10.

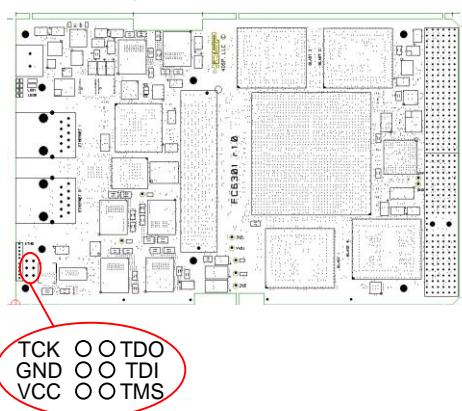


Figure 7: JTAG connector location.

4.10 Power supply

The Power is supplied to the FC6301 via the CompactPCI connectors. Several DC-DC converters generate the appropriate voltage rails for the different devices and interfaces present on board. The FC6301 power distribution is as follows:

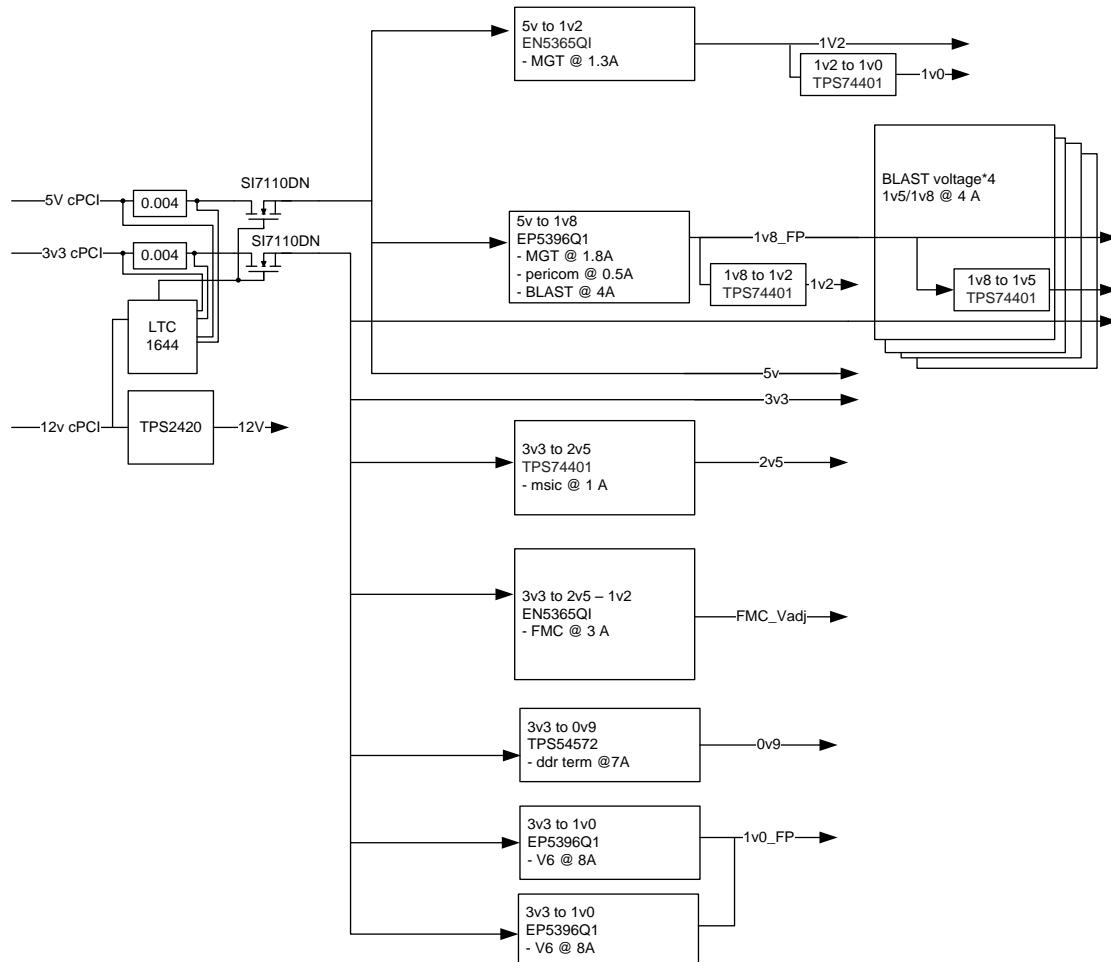


Figure 8: FC6301 power distribution

Device/Interface	Voltage	Maximum supported current
DCI and memory reference voltage	0.9V	6 A
Virtex-6 core	1V	16A
CPLD, BLAST sites	1.8V	8A
Virtex-6 Vccaux, Virtex-6 bank connected to A/D daughter card, EP80579	2.5V	2A
CPLD, PCI bridge, power generation	3.3V	11A
power generation	5V	12A
Front Panel IO daughter card	12V	2A
MGT power supply	1 V, 1.2V	2A, 1.5A

Table 15 : Power supply

4.11 Hotswap

Hot Swap is the act of removal and insertion of cards into a platform while that system is operational. This process should not cause any failures on the systems power supply and system's I/O signals. Protection of the card's circuitry also needs to be taken into account in this process.

A compact PCI board can implement three different types of hot swap:

- Non Hot Swap do not have hot swap features
- Basic Hot Swap boards have the minimum features required
- Full Hot Swap have the minimum requirements plus the ability for software connection control

The Pericom bridge is a hot swap friendly device but full hot swap is not supported. A hot swap controller is required to monitor all power levels, pre-charge the cPCI signals and to switch the backend power on and off. The LTC1643A hot swap controller from linear technologies is used. For more information on hot swap refer to the hot swap specifications.

4.12 Power and temperature monitor

Two ADT7411 devices are used to monitor the power on the different voltage rails as well as the temperature. The ADT7411 data are constantly passed to the Virtex-6 device. Measurements can be accessed from the host computer via the PCI bus.

Parameter:	Device 1	Formula
On-chip temperature	ADT7411 Die Temperature	
On-chip AIN0 (V_{DD})	+3.3V	
External temperature	FPGA A temperature	
External AIN3	12V	$AIN3 * (1249/249)$
External AIN4	1V0	$AIN4$
External AIN5	3V3	$AIN5$
External AIN6	1V2	$AIN6$
External AIN7	MGT1V2	$AIN7$
External AIN8	MGT1V0	$AIN8$

Table 16: Monitoring device 1 connections

Parameter:	Device 2	Formula
On-chip temperature	ADT7411 Die Temperature	
On-chip AIN0 (V_{DD})	+3.3V	
External AIN1	BLAST0_vcore	AIN1
External AIN2	BLAST2_vcore	AIN2
External AIN3	5V	AIN3*(1249/249)
External AIN4	0V9	AIN4
External AIN5	VADJ	AIN5
External AIN6	1V8	AIN6
External AIN7	12V current	Tbd
External AIN8	2V5	AIN8

Table 17: monitoring device 2 connections

5 Environment

5.1 Temperature

Operating temperature

- 0°C to +60°C (Commercial)
- -40°C to +85°C (Industrial)

Storage temperature:

- -40°C to +120°C

5.2 Convection cooling

The air flow provided by the chassis fans the FC6301 is enclosed in will dissipate the heat generated by the on board components. A minimum airflow of 300 LFM is recommended.

Optionally a low profile heat sink/fan can be glued on top of the Quad ADC. The card has a fan power connection that can be switch on and off under carrier card control (TBD).

For standalone operations (such as on a Xilinx development kit), it is highly recommended to blow air across the FMC and ensure that the temperature of the devices is within the allowed range. 4DSP's warranty does not cover boards on which the maximum allowed temperature has been exceeded.

6 Safety

This module presents no hazard to the user.

7 EMC

This module is designed to operate from within an enclosed host system, which is build to provide EMC shielding. Operation within the EU EMC guidelines is not guaranteed unless it is installed within an adequate host system. This module is protected from damage by fast voltage transients originating from outside the host system which may be introduced through the system.

8 Warranty

	<i>Hardware</i>	<i>Software/Firmware</i>
Basic Warranty (included)	1 Year from Date of Shipment	90 Days from Date of Shipment
Extended Warranty (optional)	2 Years from Date of Shipment	1 Year from Date of Shipment

Appendix A: Errata

PCB revision 2.1

- SPI FLASH not supported.